MA6J786Y

Silicon epitaxial planar type

For high speed switching circuits

■ Overview

MA6J786Y is optimal for general circuit supplies.
The assembly of 3 MA3X786 elements in parallel in one package.

■ Features

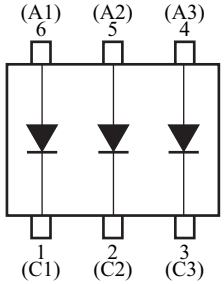
- Forward current (Average) $I_{F(AV)}$ = 100 mA rectification is possible
- Short reverse recovery time t_{rr} , optimum for high-frequency rectification
- Low forward voltage V_F and good rectification efficiency

■ Package

- Code
  SMini6-F1
- Pin Name
  1: Cathode 1 4: Anode 3
  2: Cathode 2 5: Anode 2
  3: Cathode 3 6: Anode 1

■ Marking Symbol: M8C

■ Internal Connection



■ Absolute Maximum Ratings T_a = 25°C

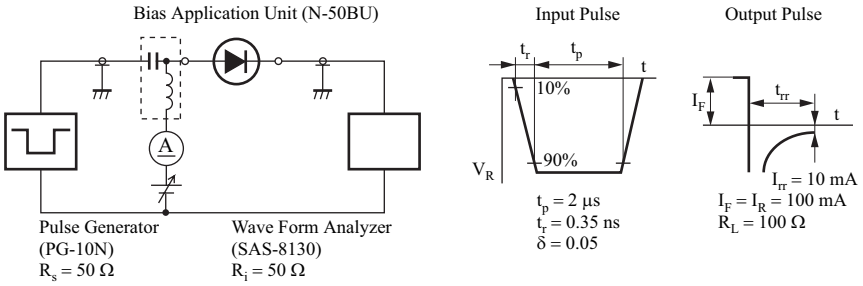
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Maximum peak reverse voltage	V_{RM}	30	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics T_a = 25°C±3°C

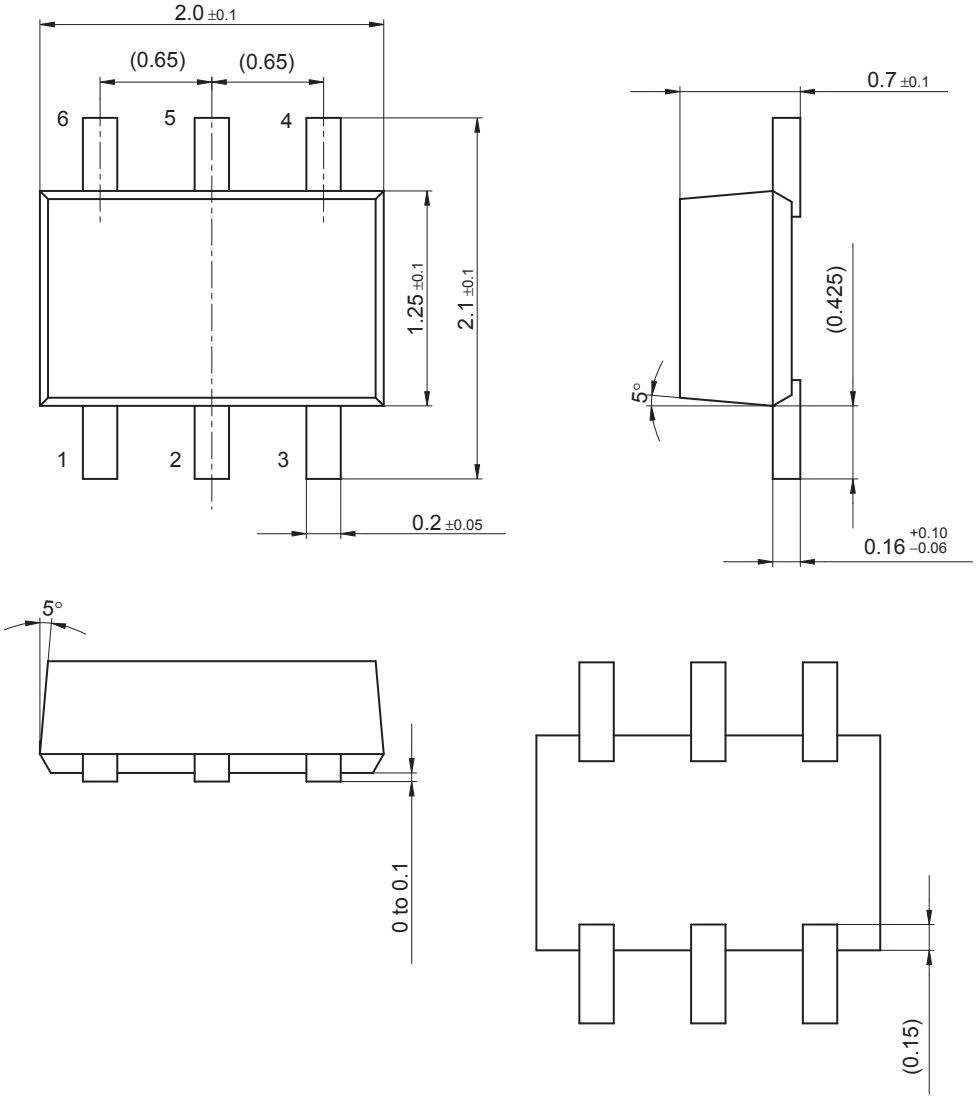
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	I_F = 100 mA			0.55	V
Reverse current	I_R	V_R = 30 V			15	μA
Terminal capacitance	C_t	V_R = 0, f = 1 MHz		20		pF
Reverse recovery time *1	t_{rr}	$I_F = I_R$ = 100 mA, I_{rr} = 0.1 × I_R , R_L = 100 Ω		1.0		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. *1: t_{rr} measurement circuit



SMini6-F1

Unit: mm



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